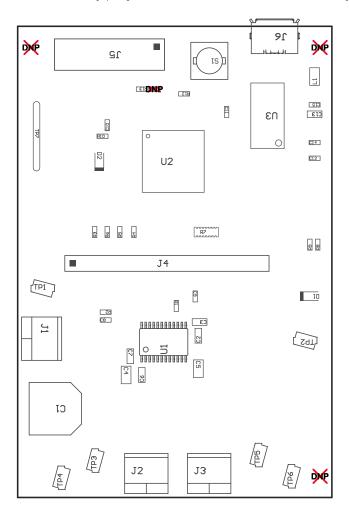
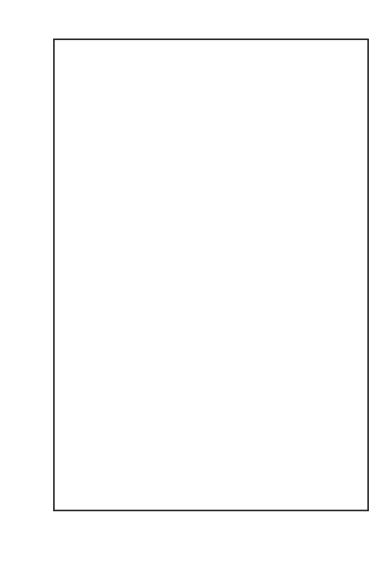
- ZZ1 These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ2 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ3 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- ZZ4 Shorting plug TP7 shall be raised to minimum height of 250mils above PCB



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #:TIDA-00867	REV: A	SUN REV:	: Not In VersionControl	
	TID #: N/A				
PLOT NAME = Top Assembly Drawing	GENERATED : 9/14/2	015 3:19:29	PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00867	REV: A	SUN REU	: Not In VersionControl	
	TID #: N/A				
PLOT NAME = Bottom Assembly Drawing	GENERATED : 9/14/2	015 3:19:30	PM	TEXAS INSTRUMENTS	

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